Docket No.: 4444-0124P

Application No. 10/646,696
Amendment dated May 24, 2006
Reply to Office Action of February 24, 2006

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An Internet automatic electrical data system, comprising:

a process controller, used to process ~~the~~ an analyzing order for integrated circuit (IC)

packages entrusted by clients;

a working database coupled to said process controller, used to store the IC package

parameters ~~input~~ inputted by said ~~a client~~ clients;

a condition parameter database coupled to said process controller to provide the condition

parameters relative to the model of the IC package entrusted by said clients;

an electrical simulation and analyzing software used to analyze said IC package

parameters ~~input~~ inputted by said clients, and said condition parameters provided by said

condition parameter database;

a report form generator coupled to said electrical simulation and analyzing software to

generate ~~the~~ a report form of ~~analyzing result~~ analyzed results; and

replying means coupled to said report form generator to send said report forms to said

clients.

2. (Currently Amended) ~~A~~ The system of claim 1, wherein said ~~client transmits~~ clients

transmit said IC package parameters through ~~the~~ Internet.

3. (Currently Amended) ~~A~~ The system of claim 1, wherein said replying means sends

said report forms to said clients ~~comprises the usage of the an~~ utilizing at least one of electronic

mail and facsimile.

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4. (Currently Amended) A The system of claim 1, wherein said process controller accesses said condition parameters from said condition parameter database, and then transfers said condition parameters along with said IC package parameters input inputted by said clients to said electrical simulation and analyzing software.

5. (Currently Amended) A The system of claim 1, wherein the IC package types provided by said condition parameter database comprise BGA (ball grid array), BCC, QFP, SOP, QFN (quad flat no-lead), Flip Chip, CSP (chip scale package), and WLCSP (wafer level chip scale package).

6. (Currently Amended) A The system of claim 1, wherein said IC package parameters input inputted by said clients comprises comprise the number of I/O (input and output) terminals, package type, substrate layer, substrate thickness, information about lead frame, and frequency.

7. (Currently Amended) A The system of claim 1, wherein said electrical simulation and analyzing software constructs a three-dimensional model according to said IC package parameters and said condition parameters.

8. (Currently Amended) A The system of claim 7, wherein said electrical simulation and analyzing software calculates the resistance, inductance and capacitance of said IC package according to said IC package parameters and said condition parameters.

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9. (Currently Amended) A The system of claim 1, wherein said electrical simulation and analyzing software transfers said analyzing result to said report form generator.

10. (Currently Amended) A method for automatic automatically analyzing electrical data through the Internet, which comprises comprising the following steps:

inputting IC package parameters for analyzing by a client;

transferring said IC package parameters to a working database for storing through the Internet;

accessing said IC package parameters from said working database and condition parameters relative to said IC package parameters from a condition parameter database by a process controller;

transferring said IC package parameters and said condition parameters to an electrical simulation and analyzing software for simulating and analyzing by said process controller to generate an analyzed result;

transferring the analyzing analyzed result to a report form generator for generating the a report form of analyzing analyzed result;

transferring said report form generator transferring said report form via said report form generator to a replying means; and

sending said report form to said clients client by said replying means.

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11. (Currently Amended) A-The method of claim 10, wherein said client transmits said IC package parameters through the Internet.

12. (Cancelled)

13. (Currently Amended) A-The method of claim 10, wherein said IC package parameters input inputted by said client comprises the number of I/O terminals, package type, the number of the substrate layer, substrate thickness, information about lead frame, and frequency.

14. (Currently Amended) A-The method of claim 10, wherein said electrical simulation and analyzing software constructs a three-dimensional model according to said IC package parameters and said condition parameters.

15. (Currently Amended) A-The method of claim 14, wherein said electrical simulation and analyzing software calculates the resistance, inductance, and capacitance of said IC package according to said IC package parameters and said condition parameters.

16. (Currently Amended) A-The method of claim 10, wherein the IC package types provided by said condition parameter database comprise BGA (ball grid array), BCC, QFP, SOP, QFN (quad flat no-lead), Flip Chip, CSP (chip scale package), and WLCSP (wafer level chip scale package).

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